

Examiner's Grp

AN 2000:37783 HCPLUS
DN 132:96561
TI Lead-free solders
IN Matsumoto, Kazuo; Muraoka, Naoki; Omoto, Takahiko; Ozaki, Masakazu
PA Ishikawa Kinzoku K. K., Japan
SO Jpn. Kokai Tokkyo Koho, 17 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2000015476	A2	20000118	JP 1998-182070	19980629
AB	Sn alloys contg. Ag 0.5-3.5, Bi 0.5-10.0, Cu 0.1-1.0, P 0.001-0.01 wt.% and microalloyed with (a) Ni 0.001-0.01, (b) Ge 0.005-0.05, (c) Te 0.001-0.01 and Ga 0.01-0.1, or (d) Co 0.001-0.01 and/or Cr 0.005-0.05 wt.% are claimed as solders. The solders are esp. useful for accurate mounting of semiconductor chips, etc. on circuit substrates.				